SBYT42M

SINTERED GLASS JUNCTION SURFACE MOUNTED RECTIFIER CURRENT: 1.25A

VOLTAGE: 1000V

Sintered glass cavity free junction

High temperature soldering guaranteed

 265° C for 10 seconds in solder bath

Fast Soft Recovery Rectifier

MECHANICAL DATA

Retardant Epoxy Polarity: color band denotes cathode

Mounting position: any

Mark: T42M

Capability of meeting environmental standard of

Complete device submersible temperature of

Operate at Ta =55°C with no thermal run away

Terminal: Plated axial leads solderable per

MIL-STD 202E, method 208C

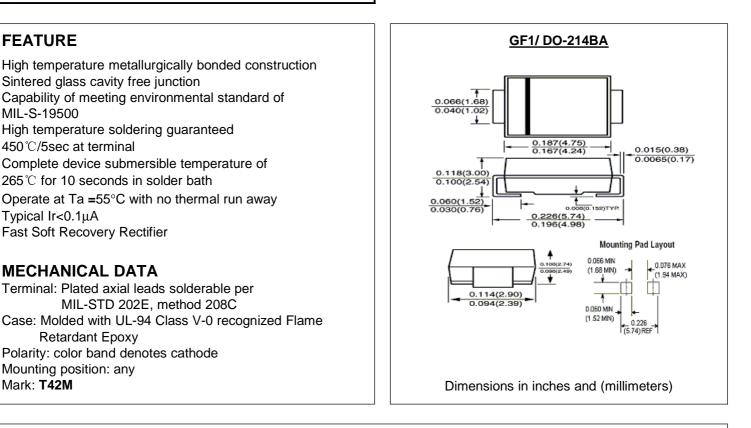
FEATURE

MIL-S-19500

Typical Ir<0.1µA

450 °C/5sec at terminal





MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half-wave, 60HZ, resistive or inductive load rating at 25°C, unless otherwise stated)

	SYMBOL	SBYT42M	units
Maximum Recurrent Peak Reverse Voltage	Vrrm	1000	V
Maximum RMS Voltage	Vrms	700	V
Maximum DC blocking Voltage	Vdc	1000	V
Maximum Average Forward Rectified Current 3/8"lead length at Ta =55°C	lf(av)	1.25	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	lfsm	30.0	A
Maximum Forward Voltage atForward Current 1.0A and 25°C	Vf	1.4	V
Maximum DC Reverse CurrentTa =25°Cat rated DC blocking voltageTa =150°C	Ir	5.0 150.0	μΑ
Maximum Reverse Recovery Time (Note 1)	Trr	200	nS
Non repetitive reverse avalanche energy $I_{(BR)R}$ =0.4A	Er	10.0	mJ
Typical Thermal Resistance (Note 2)	Rth(ja)	55.0	°C /V
Storage and Operating Junction Temperature	Tstg, Tj	-65 to +175	°C

dition If =0.5A. Ir =1.0A. Irr =

2. Thermal Resistance from Junction to Ambient, P.C.B. Mounted on 0.2×0.2" (5.0×5.0mm) copper pad areas

RATINGS AND CHARACTERISTIC CURVES SBYT42M

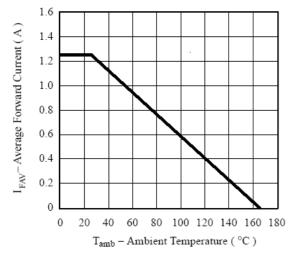


Figure 1. Max. Average Forward Current vs. Ambient Temperature

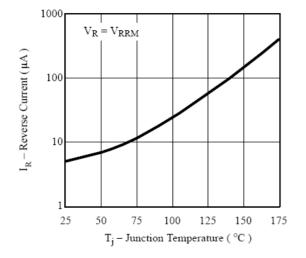


Figure 3. Max. Reverse Current vs. Junction Temperature

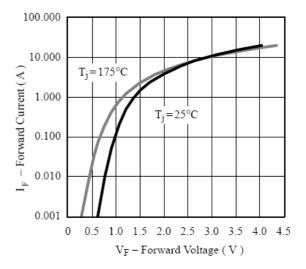


Figure 2. Max. Forward Current vs. Forward Voltage

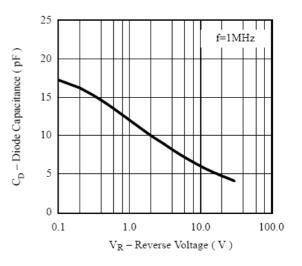


Figure 4. Diode Capacitance vs. Reverse Voltage